

Title (en)
METHOD OF ACCELERATING WOUND AND ULCER HEALING AND TREATING PERIODONTAL DISEASE.

Title (de)
METHODE ZUR BESCHLEUNIGTEN WUND- UND GESCHWÜRHEILUNG SOWIE BEHANDLUNG DER PERIODONTITIS.

Title (fr)
PROCEDE D'ACCELERATION DE LA CICATRISATION DE PLAIES ET D'ULCERES, ET DE TRAITEMENT DE MALADIE PERIODONTIQUE.

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Abstract (en)
[origin: WO9105537A1] The invention relates to methods for enhancing wound healing; enhancing gastric, duodenal, esophageal, decubitus, genito urinary ulcer and ulcerative keratitis healing; inhibiting scar formation; and treating periodontal disease in an animal by the topical, oral parenteral, transdermal or ophthalmic administration of a vitamin D compound.

Abstract (fr)
On a mis au point des procédés améliorant la cicatrisation de plaies, améliorant la cicatrisation d'ulcères gastriques, duodénaux, oesophagiens, de décubitus et génito-urinaires, et de la kératite ulcéreuse; inhibant la formation de cicatrices; et de traitement de maladies périodontiques chez l'animal par administration locale, orale, parentérale, transdermique ou ophtalmique d'un composé de vitamine D.

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